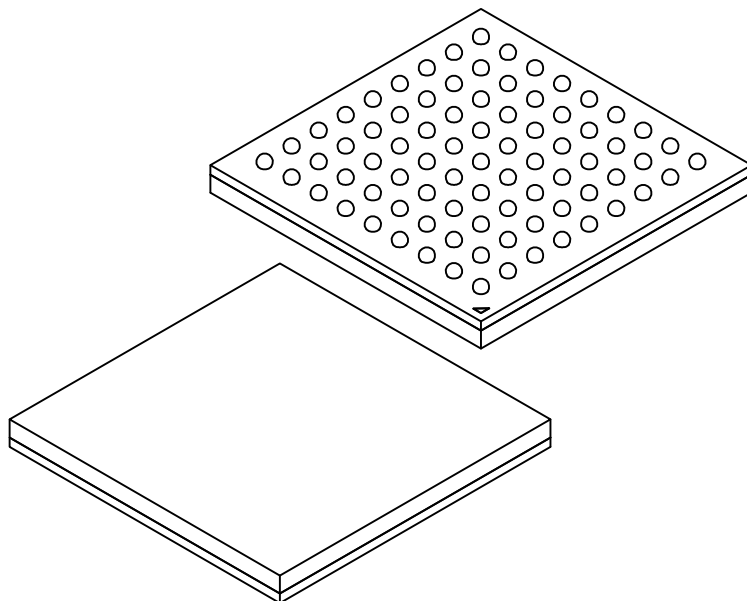


81-Ball Thin Fine-Pitch Ball Grid Array Package (4LB) - 10x10x1.2 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		81		
Pitch	e		1.00 BSC		
Overall Height	A	–	–	1.20	
Ball Height	A1	0.27	0.32	0.37	
Mold Thickness	A2	0.53 REF			
Substrate Thickness	A3	0.26 REF			
Overall Length	D	10.00 BSC			
Ball Array Length	D2	8.00 BSC			
Overall Width	E	10.00 BSC			
Ball Array Width	E2	8.00 BSC			
Ball Diameter	b	0.38	0.40	0.48	

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.